



Material Content Data Sheet



Sales Product Name		TLE5012B E9000		Issued		3. July 2019		
MA#		MA005342662						
Package		PG-DSO-8-16		Weight*		83.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.535	4.23	4.23	42306	42306
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8584	
wire	non noble metal	copper	7440-50-8	29.121	34.86	35.77	348559	357679
	noble metal	gold	7440-57-5	0.154	0.18	0.18	1840	1840
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1124
encapsulation	plastics	epoxy resin	-	4.321	5.17		51714	
	inorganic material	silicondioxide	60676-86-0	42.548	50.93	56.21	509276	562114
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9741	9741
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7783	7783
glue	plastics	acrylic resin	-	0.341	0.41		4078	
	noble metal	silver	7440-22-4	1.208	1.45	1.86	14459	18537
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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